

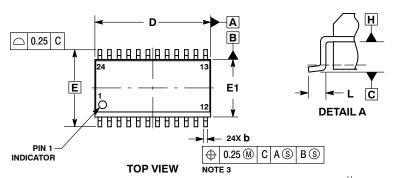


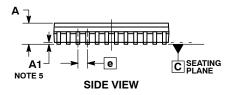
F DATE 03 JUL 2012

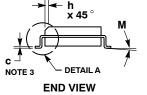
## NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
   Y14 5M 1994
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSIONS b AND c APPLY TO THE FLAT SEC-
- DIMENSIONS 6 AND c APPLY TO THE FLAT SECTION OF THE LEAD AND ARE MEASURED BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP.
   DIMENSIONS D AND E1 DO NOT INCLUDE MOLD
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D AND E1 ARE DE-TERMINED AT DATUM H.
- FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

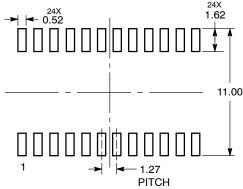
TOUT OIL THE THOU				
	MILLIMETERS			
DIM	MIN	MAX		
Α	2.35	2.65		
A1	0.13	0.29		
b	0.35	0.49		
C	0.23	0.32		
D	15.25	15.54		
Е	10.30 BSC			
E1	7.40	7.60		
е	1.27 BSC			
h	0.25	0.75		
L	0.41	0.90		
М	0 °	8 °		





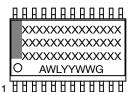


## RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

## GENERIC MARKING DIAGRAM\*



XXXXX = Specific Device Code A = Assembly Location

WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SOIC-24 WB		PAGE 1 OF 1

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.